

Burn-in & Test Socket Workshop

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Computer Society





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Technical Program

Keynote Address Tuesday 3/05/02 8:00PM

"Tooling: The Other 'Capital' Equipment"

Steven B. Strauss ITTO Manager Intel Corporation

Tooling: The Other "Capital" Equipment



Steven B Strauss Intel Test Tooling Operation Manager Chandler, Arizona

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Key Messages:

- We have just experienced one of the worst economic downturns in the history of this industry
- Technical challenges continue to accelerate
- Increasing costs have driven changes in Capital Equipment for Test
- The Tooling Supply industry has not changed to meet customer needs in solutions, cost, or capability
- It's time

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The economic world we live in: Semiconductor Industry Cycles





"If the automobile industry advanced as rapidly as the semiconductor industry, a Rolls Royce would get 500,000 miles per gallon of gas and it would be cheaper to throw it away than park it."

– Gordon E. Moore Chairman Emeritus, Intel Corporation

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The Technical World we live in: Extending Moore's Law

Transistors doubling every 2 years toward a billion transistors



The Technical world we live in: The Volume Lifecycle



The Technical World we live in: Power Delivery

- How do you deliver a lot of noise free power quickly
- Power in = Heat
 Out
- Capabilities needed

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Issue

- 2X improvement in capacitance and inductance needed / generation
- Need to optimize the complete silicon to tester power delivery solution



The Technical World we live in: Power Density will get worse



How rapidly can we innovate new thermal solutions / interface materials ?

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Communications Products Packaging Challenges

TSOP





The Manufacturing World we live in: Test Flow Revolution

Fab

Structural Wafer Sort

Assembly

STDBI

Structura Class

Functional Class

PPV

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The test industry has changed

 Implemented advanced DFT to manage test complexity

- Eliminate capability treadmill
- Enable parallel test in complex designs
- Migrate significant percentage of test content to less expensive structural test
 - Enables capital cost reduction
 - Deliver state-of-the-art capabilities
 - Simplified tester hardware designs

STATISTICS IN ALL OF

Optimized content and flow















Wafer Test: Probe Cards, Probes, int_{el}. Space transformers



Big Boards and Sockets: Burn in, Massively parallel test and fusing int_{el}.

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Tooling:

Provides a temporary Thermal Mechanical and/or Electrical interface to the DUT Is custom to products Is dependent on and customized to: Packaging form factors, Electrical and Thermal requirements and Device Function Has demand that is driven by product ramp cycles and is renewed and upgraded by product, package etc... Provides supplier and supply chain challenges like no other commodity Is a technology, development and HVM enabler! int_

What does it takes to deliver tooling in this environment?



Tooling Suppliers are not keeping up!



The Treadmill Challenge in Tooling

- NPI increasing at 40% to 50% per year
 - More custom designs
- Steep Product Ramps -GIRTFT
- Product Health is a big lever
- Tooling and Service costs are increasing as an overall percentage of test cost

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Depreciation Tooling Support Labor



Tooling suppliers

- Are there any "turn key" tooling suppliers? The tooling industry is fragmented
- The Capital Analogy:
 - Buy capital equipment One stop shopping
 - You don't buy the pieces from 2-3 suppliers!
- Lets buy a Burn In board
 - 1 supplier for design
 - 1 supplier for PCB manufacturing
 - 1 supplier for sockets

• Who stands by the final product? The Customer ?

The Tooling Supply Chain Needs to provide Solutions, not components intel.

Today's Tooling Supply Chain

- Tooling suppliers fall into 2 categories
 - Component manufacturers
 - Integrators or Assemblers
- A typical tooling supply chain contains 2-4 poorly synchronized suppliers
 - -Design
 - -Custom component design and manufacturing
 - Assembly or Integration
 - -HVM support

This industry infrastructure will not achieve the requirements of the next generations intel.

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The Next Generation Tooling Supply Chain

- Is proactively on the "treadmill"
 - Technically
 - Economically
 - Logistically
- Enables fungible designs that last 2-3 process generations
- Is in sync with the specific technologies of the customers
- Provides turn key solutions
- Has 2 4 weak lead times

 Is low, low, low cost and continues to drive costs intel.

What it takes

- Evolution will not yield these goals!
- The scaling treadmill that the industry has relied upon needs to be replaced by disruptive technologies
- If you want to survive you must:
 - invest in disruptive technologies
 - cannibalize your current ones

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 acknowledge that your business model will be completely different in 2 years.

Can you do this? If not you won't survive! About 1/2 of you will be around in 2 years Will you be one of them? "We sometimes refer to the definition of insanity as doing the same thing the same way over and over again, hoping for a different result. If you want to achieve different results -- *better results* -- you have to do things differently. Success is not accidental. It happens because people plan carefully and they lay the necessary groundwork to get the right result in the end."

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-- Craig Barrett President and CEO, Intel Corporation December 29, 2000